

IN THE CLAIMS:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~striketrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please AMEND claim 5 and ADD new claim 28 in accordance with the following:

1. (ORIGINAL) An electronic device having mounted thereon a microelectromechanical system element comprising a micromachine component and electronic component for operation of said micromachine component formed on a substrate, in which an operating space for said micromachine component is defined by said substrate and a lid bonded covering an active surface of said substrate, and said electronic component and wiring patterns of said lid are electrically connected at a bonded part of said substrate and said lid.
2. (ORIGINAL) An electronic device as set forth in claim 1, in which said bonded part is an ultrasonic bonded part of said substrate and said lid.
3. (PREVIOUSLY PRESENTED) An electronic device as set forth in claim 1, in which said substrate and/or said lid further have a cavity at said operating space side.
4. (PREVIOUSLY PRESENTED) An electronic device as set forth in claim 1, in which said substrate and a lid having no wiring pattern further comprise, between them, an intermediate member provided with an opening for operation of said micromachine component and wiring patterns and said electronic component and the wiring patterns of said intermediate member are electrically connected.
5. (CURRENTLY AMENDED) An electronic device as set forth in claim 2, in which said substrate, said lid, and an intermediate member arranged ~~in accordance with need between~~ said substrate and said lid further comprise a second continuous ultrasonic bonded part formed in contact with an outer periphery of ~~said~~ an operating space side of said substrate and other members without interruption.

6. (PREVIOUSLY PRESENTED) An electronic device as set forth in claim 1, in which said substrate and/or said lid further comprise conductor-filled vias formed passing through them in a thickness direction.

7. (ORIGINAL) An electronic device as set forth in claim 4, in which said intermediate member further comprises conductor-filled vias formed passing through it in a thickness direction.

8. (PREVIOUSLY PRESENTED) An electronic device as set forth in claim 1, which further comprises a bonded sealing resin surrounding an outside surface of said bonded part.

9. (PREVIOUSLY PRESENTED) An electronic device as set forth in claim 1, in which a plurality of said electronic devices are those produced batch-wise at the same time by a wafer level package process.

10-27. (CANCELLED)

28. (NEW) An electronic device, comprising:
a micromachine component;
an electronic component to operate the micromachine component; and
a lid and a substrate bonded without interruption at an outer periphery of the lid and the substrate and defining a space in which the micromachine component is mounted, the electronic component being formed on the substrate, wiring patterns of the lid electrically connected to the electronic component at the bonded part of the lid and substrate.